JIEP & CPMT

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As the President of the IEEE Components, Packaging and Manufacturing Technology (CPMT) Society, I am deeply honored by Dr Tsukada's invitation to write this preface for the JIEP Journal.

The discovery of transistor effect in 1947 and the invention of integrated circuits eleven years later laid the foundation for the science and technology of electronics. The myriad applications of electronics are everywhere in our daily lives, extensively shaping the way we work, live, communicate, and play. The progress of the industry is being increasingly propelled by the forces of the market and technology. In recent years, the electronics product market is being significantly dominated by the consumer market. On the other hand, the silicon technology long driven by CMOS scaling is being driven by the duality of "More Moore" and "More than Moore". Electronic packaging stands at the final stages of the electronic product supply chain in product design, development and manufacturing technology supply chain. Electronic packaging technologies are crucial to the performance, functionality, form factor, and cost of the many electronic products delivered to the global market place. In this consumer driven market place, electronic packaging technology is experiencing a renaissance with inventions and innovations across the technology spectrum from 3D-IC TSV, WLCSP and fanout, 4th generation flip chip and Cu pillar, fine pitch Cu wire bond, and system integration based upon different facets of SiP and PoP. These are testament to the vitality, and creativity of the packaging profession. With the world coming out of deep economic depression, one may expect to see an accelerated pace of implementation of new ideas and novel concepts of packaging technologies into consumers' hands across the globe.

The IEEE CPMT Society is one of the 39 technical societies of Institute of Electrical and Electronic Engineers (IEEE), and our membership encompasses the broad community of technical professionals from industry, academia, and research institutes. Our members are from all walks of the engineering and scientific disciplines including electrical engineering, mechanical engineering and mechanics, materials sciences, chemistry and physics, manufacturing technologies, and many others. The nature of our profession requires multidisciplinary collaboration and cross fertilization. As such, the CPMT Society organizes and sponsors high quality technical conferences and workshops, high quality technical journals and newsletters, and educational programs, member and chapter activities across the globe. In respect to all these activities, the main goal is always to provide platforms for networking, communication and mutual collaboration, ultimately for the advancement of our professions.

Our industry has become a global industry. Universities and research institutes engaging in microelectronic packaging research and development are wide spread across the globe. An important initiative for CPMT is to develop different ways to serve the professional community wherever they are in the world. CPMT collaborates with other technical societies towards this objective in many different global regions.

JIEP Journal is the leading Electronic Packaging Journal in the Japanese language, while CPMT Transactions publish all materials in English. JIEP and CPMT together represent a broad constituency of engineers and scientists in the global electronic packaging community. Many of CPMT Japan Chapter members are members of JIEP. Together, we share a common interest in technology advancement for the benefit of people around the world. Technology is without boundaries. So is learning, and so is friendship.

We would like to thank the JIEP Editorial Board for this opportunity to convey a message to the authors and readers of this very prestigious journal. On behalf of the CPMT Society, we would like to send our sincere greetings to the members of JIEP.

付記：2008年、私が当学会会長るとき、IEEE CPMTのマネジメントとの間で両学会の交流強化を合意しましたが、そのフォローの意味も加えて、今回の巻頭言を編集委員会合意のもとにチェン氏にお願いしました。

(編集委員会委員：塚田 裕)